US00D864132S

(12) **United States Design Patent**
**Sawada**

(10) **Patent No.: US D864,132 S**
(45) **Date of Patent: ** Oct. 22, 2019**

(54) **POWER SEMICONDUCTOR MODULE**

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(73) Assignee: **ROHM CO., LTD.**, Kyoto (JP)

(**) Term: **15 Years**

(21) Appl. No.: **29/609,637**

(22) Filed: **Jul. 3, 2017**

(30) **Foreign Application Priority Data**

| | | |
|---|---|---|
| Jan. 5, 2017 | (JP) | 2017-000031 |
| Jan. 5, 2017 | (JP) | 2017-000033 |
| Jan. 5, 2017 | (JP) | 2017-000034 |

(51) **LOC (12) Cl.** ............................................ **13-03**

(52) **U.S. Cl.**
USPC ........................................................ **D13/182**

(58) **Field of Classification Search**
USPC ................ D13/182; 257/678, 684, 690, 691; 361/679.01, 713, 728, 736, 760, 761, 772, 361/775, 783, 820; 174/250, 253; 438/15, 25, 26, 51, 55, 63, 64, 106
CPC . H01L 21/00; H01L 2224/42; H01L 2224/43; H01L 2021/00; H01L 2021/02; H01L 2021/04; H01L 21/4814; H01L 21/4846; H01L 21/4871; H01L 21/67144; H01L 23/12; H01L 23/13; H01L 23/14; H01L 23/147; H01L 2924/171; H01L 2924/1711; H01L 2924/1715; H01L 2924/17151; H01L 2924/181; H01L 2924/1811; H01L 2924/1815; H01L 2924/19042; H01L 2924/1905; H01L 2224/08054; H01L 23/58; H05B 41/14; H02B 6/4201; G02B 6/4256; G02B 6/4257; G02B 6/4261; G02B 6/4262; G02B 6/428; G02B 6/4281; H05K 1/14; H05K 1/141; H05K 1/142; H05K 1/144; H05K 1/18; H05K 1/181; H05K 1/182; H05K 1/026
See application file for complete search history.

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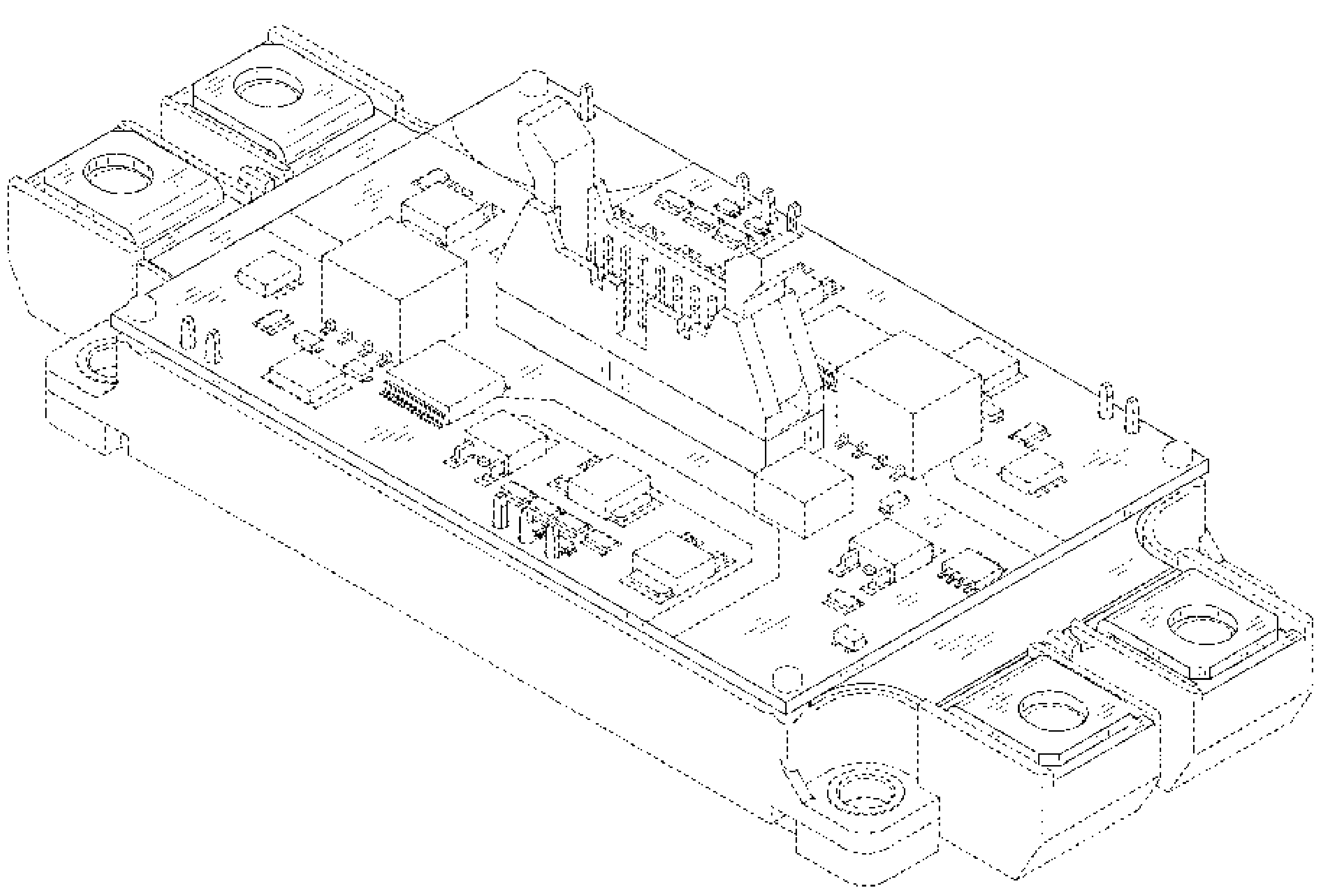
(57) **CLAIM**

The ornamental design for a power semiconductor module, as shown and described.

## DESCRIPTION

FIG. **1** is a front, top, and right side perspective view of a first embodiment of a power semiconductor module showing my new design;
FIG. **2** is a front view thereof;
FIG. **3** is a rear view thereof;
FIG. **4** is a top plan view thereof;
FIG. **5** is a right side view thereof;
FIG. **6** is a left side view thereof;
FIG. **7** is a front, top, and right side perspective view of a second embodiment of a power semiconductor module showing my new design;
FIG. **8** is a front view thereof;
FIG. **9** is a rear view thereof;
FIG. **10** is a top plan view thereof;
FIG. **11** is a right side view thereof; and,
FIG. **12** is a left side view thereof.
The features shown in broken lines in the drawings depict portions of the article that form no part of the claimed design. The dash-dotted lines denote the boundary of the claim and form no part of the claimed design.

**1 Claim, 12 Drawing Sheets**



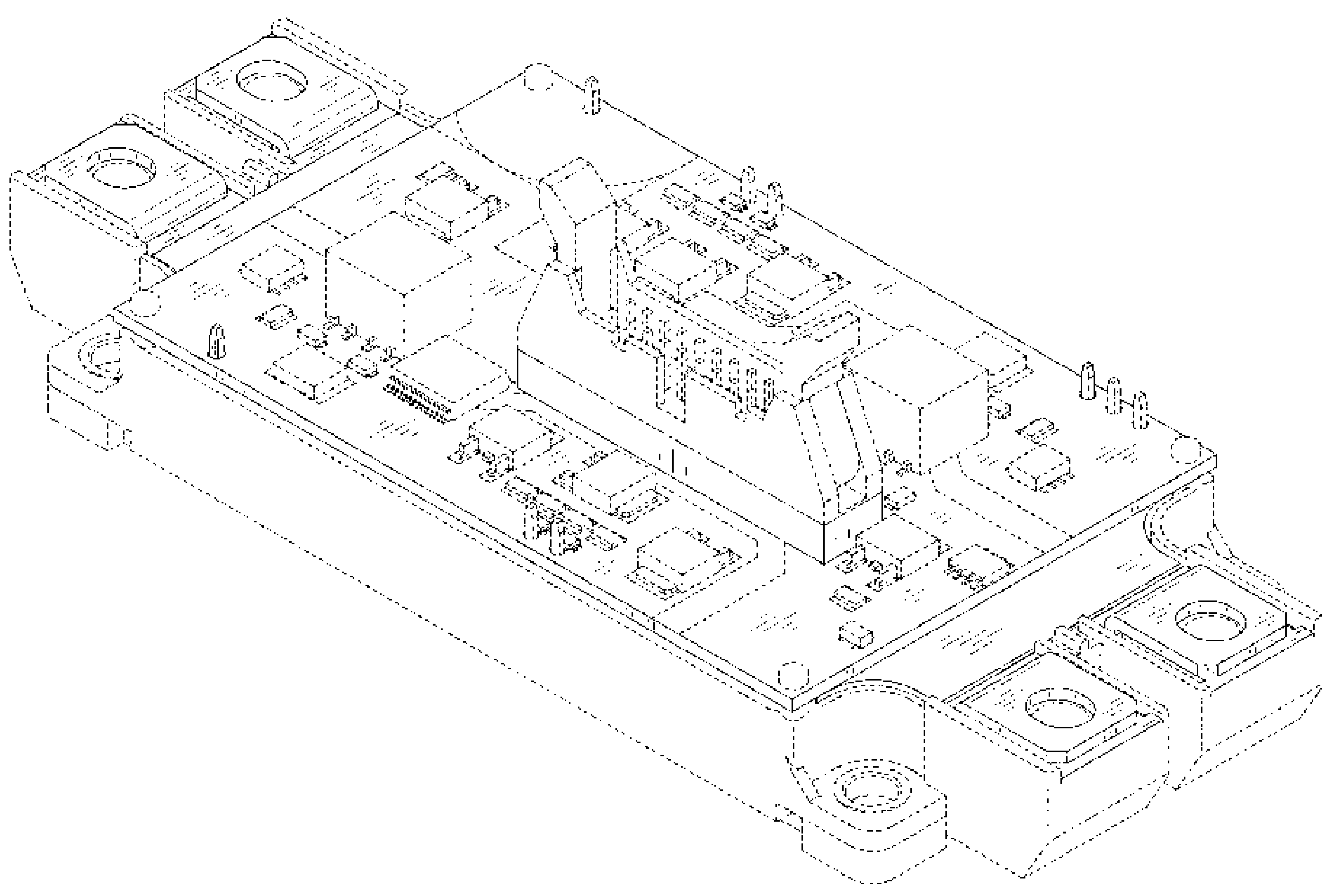


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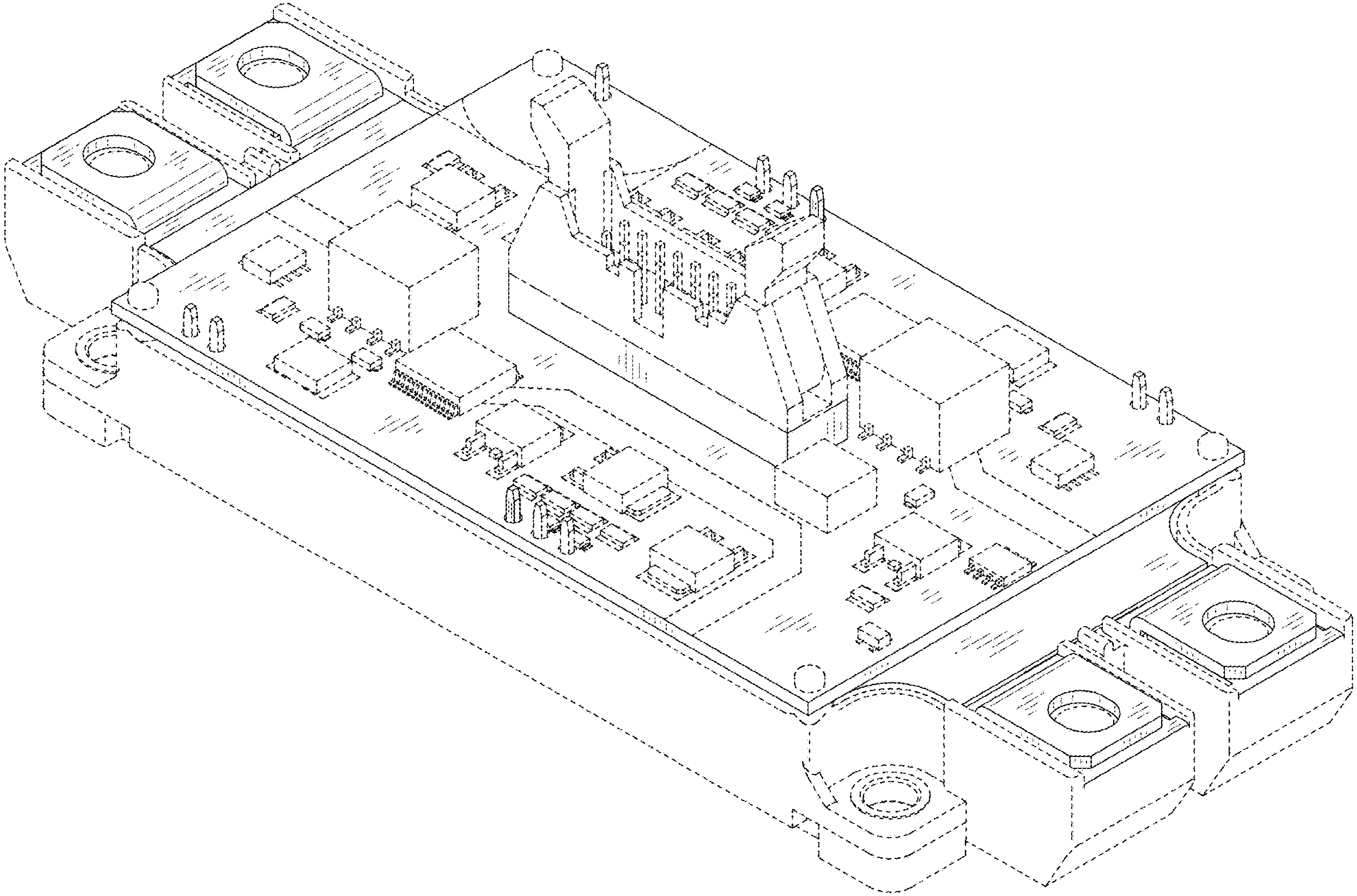
FIG.1



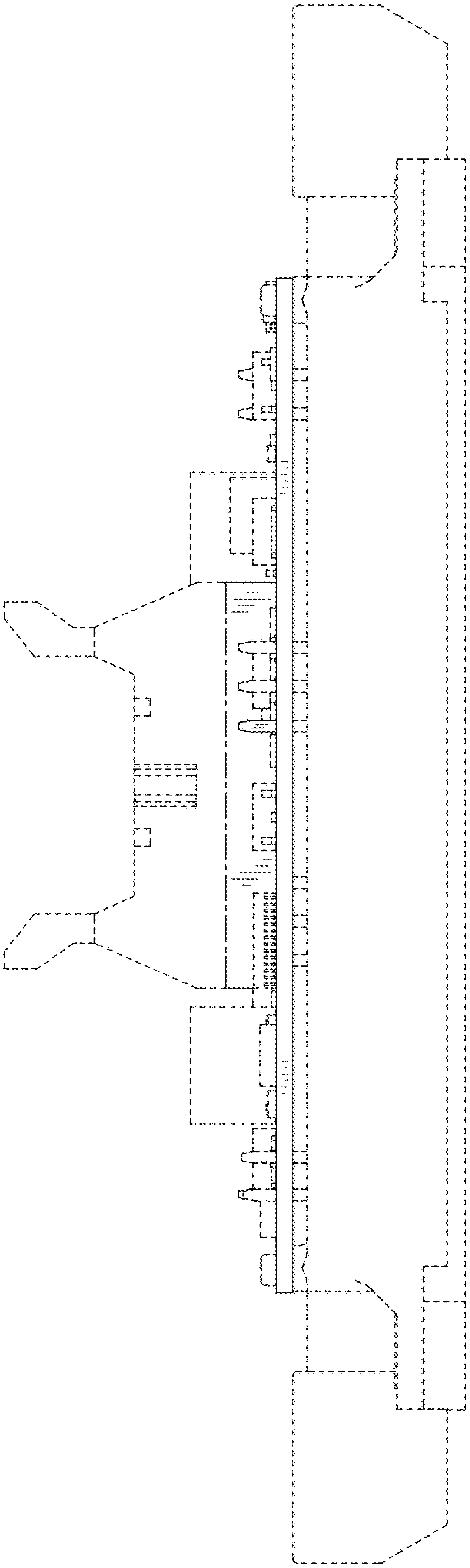


FIG.2

FIG.3

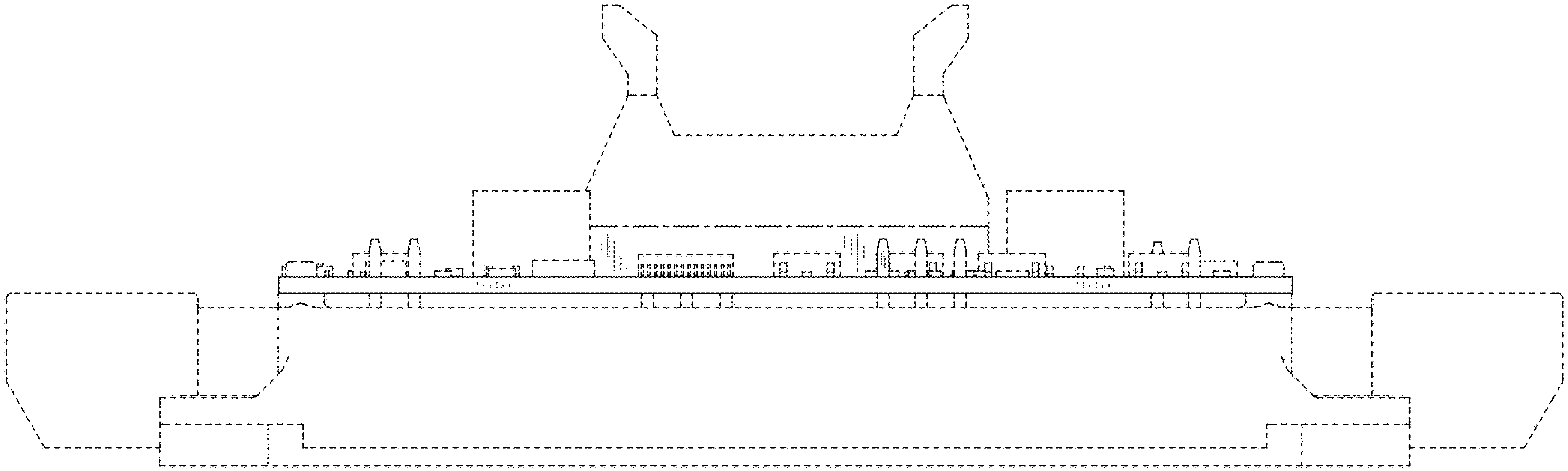


FIG.4

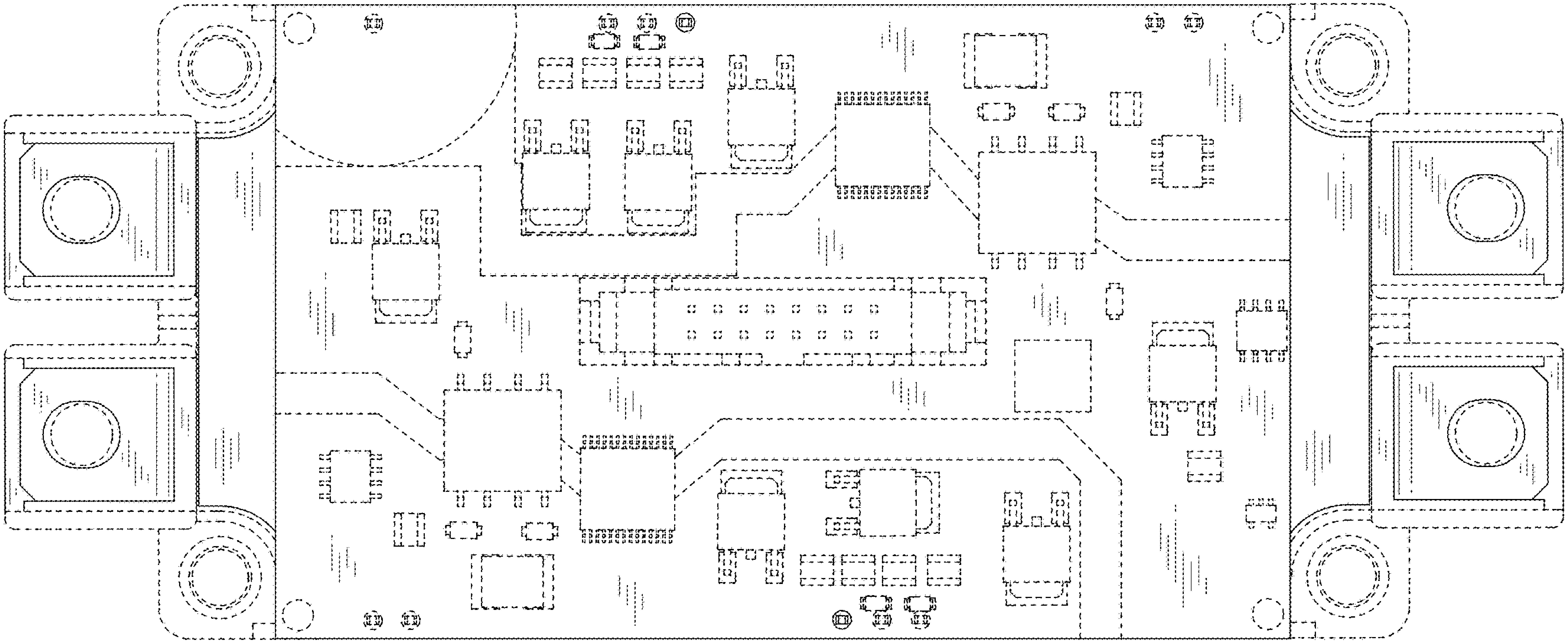


FIG.5

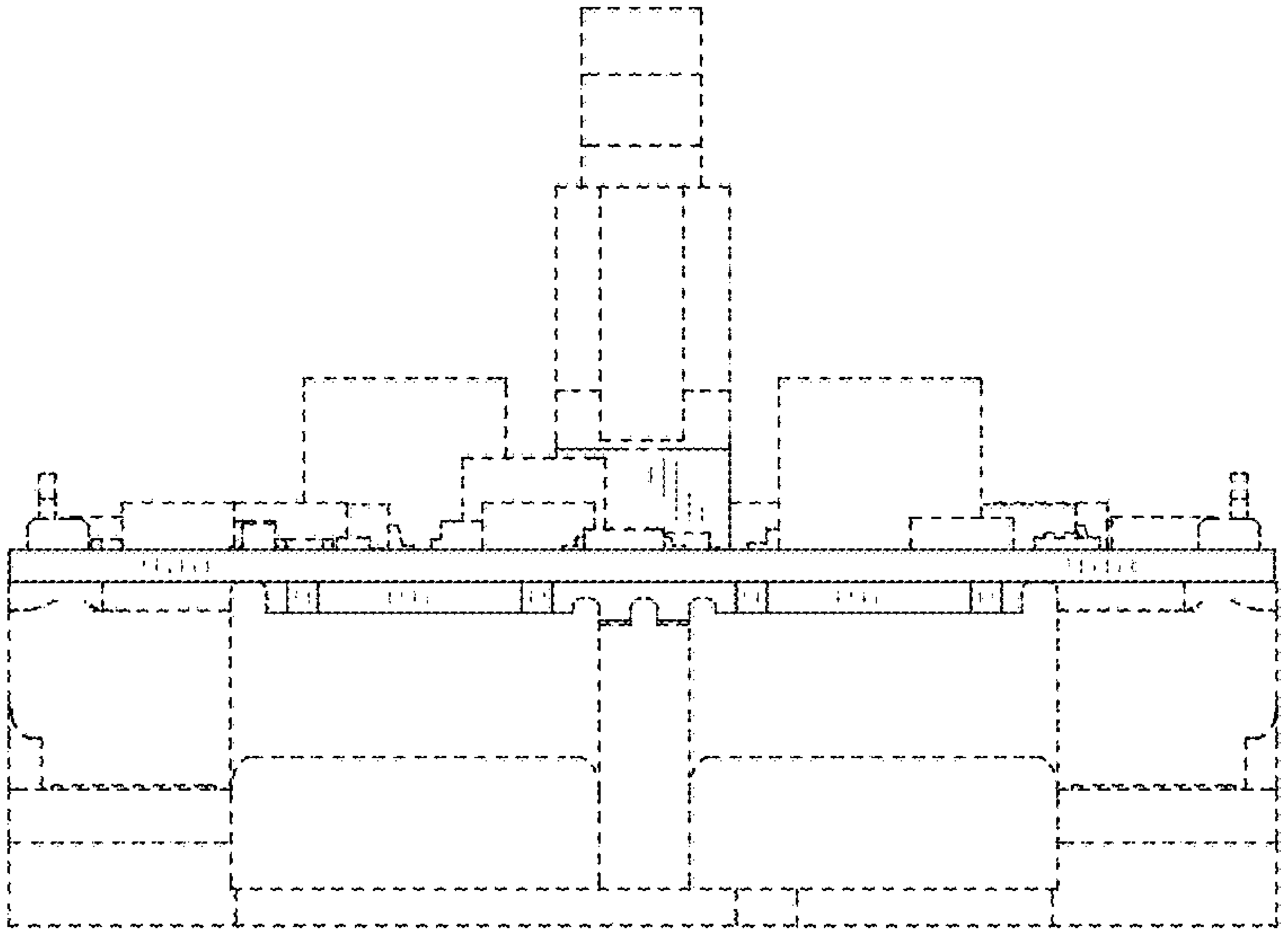
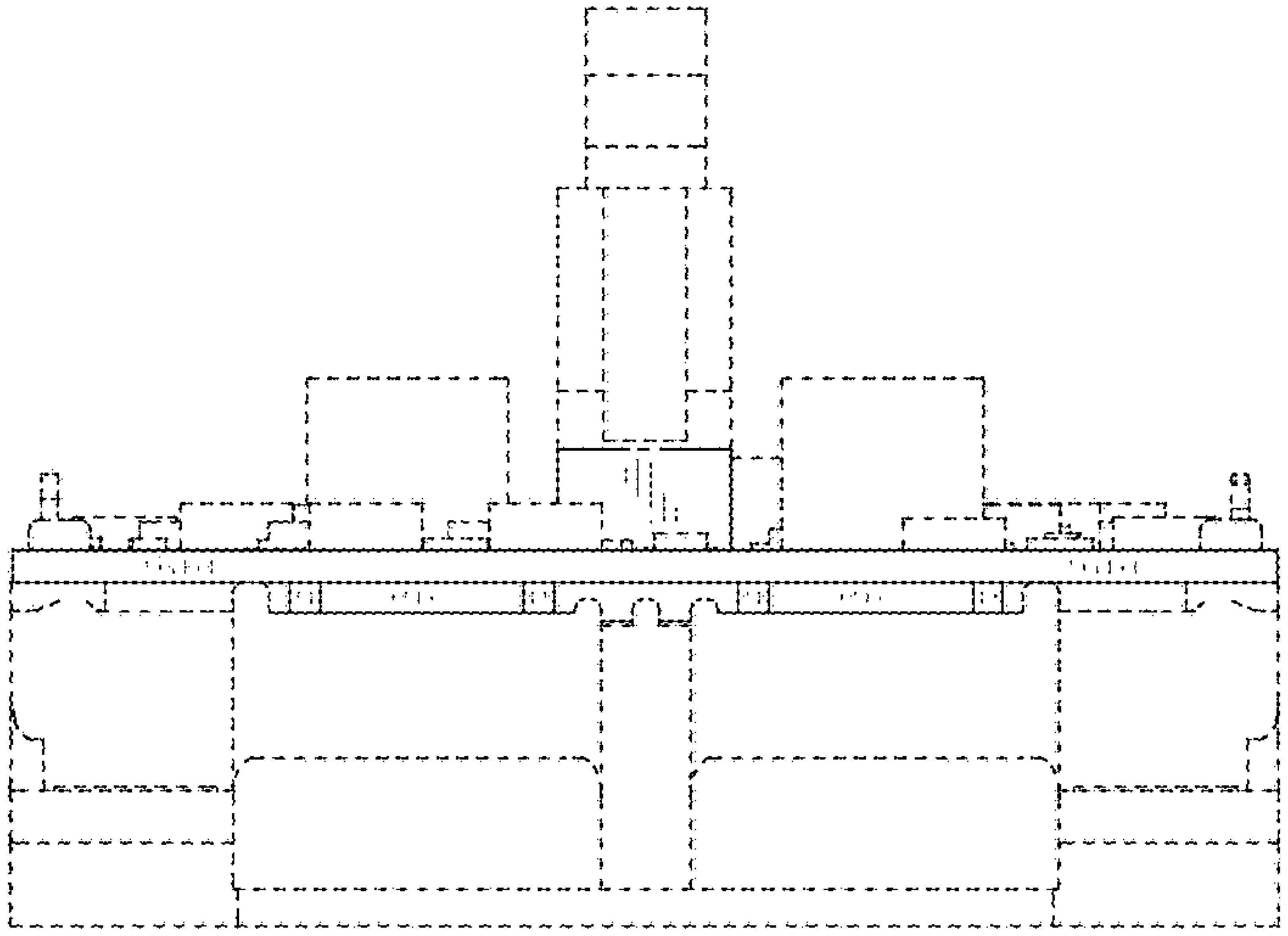


FIG.6



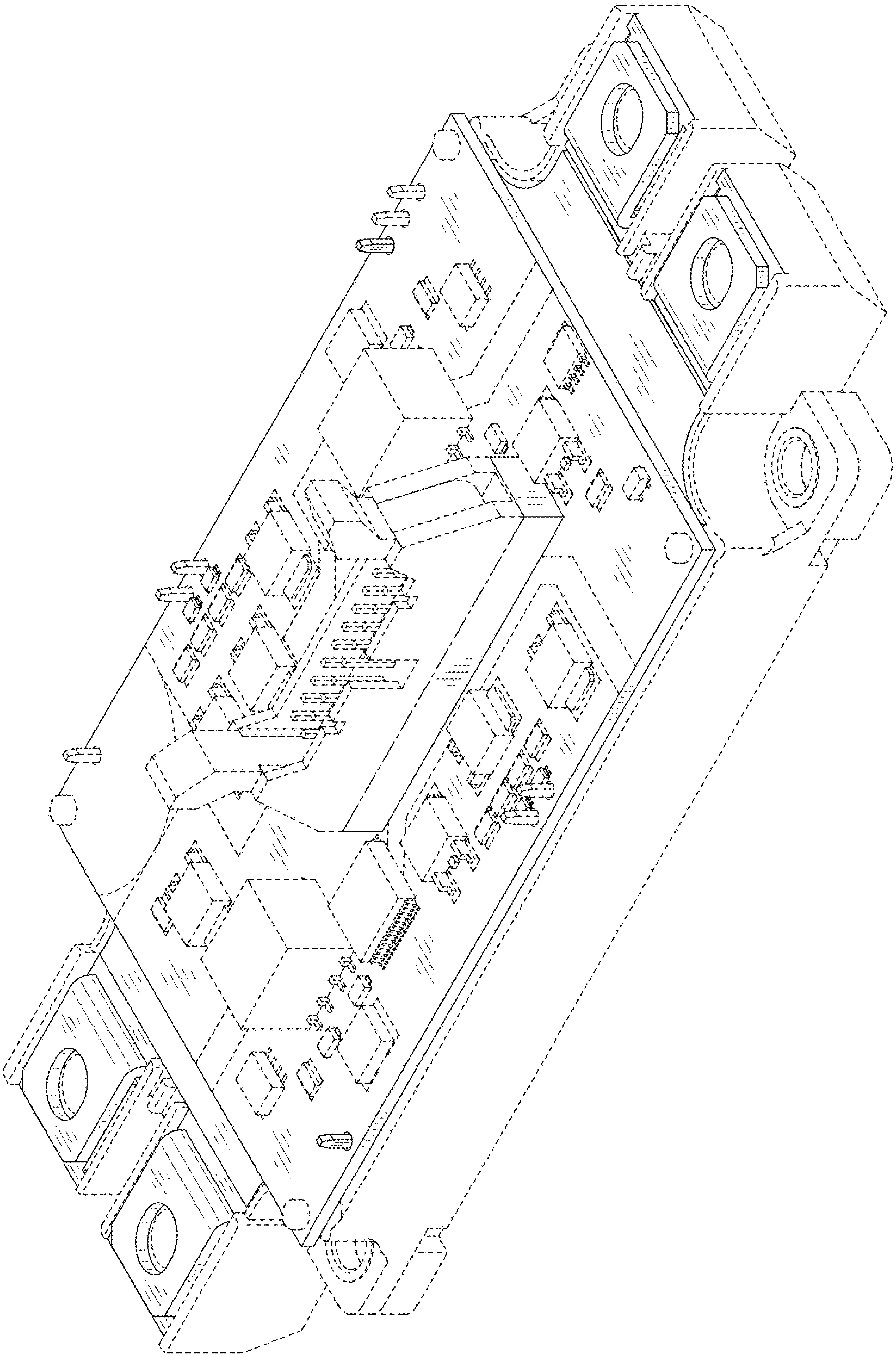


FIG.7

FIG.8

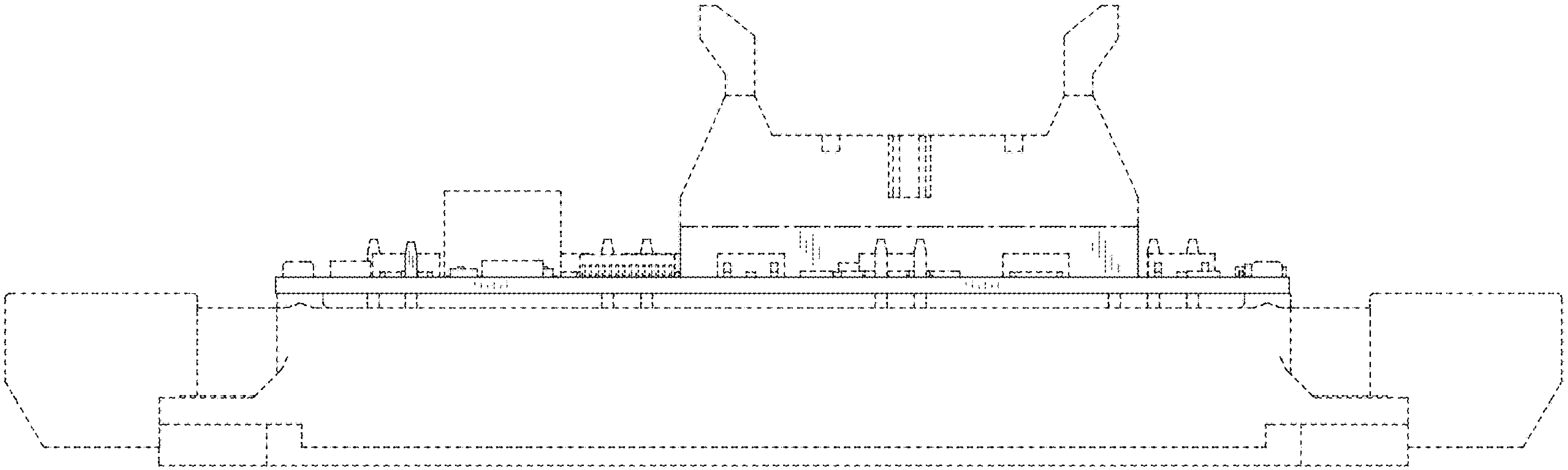
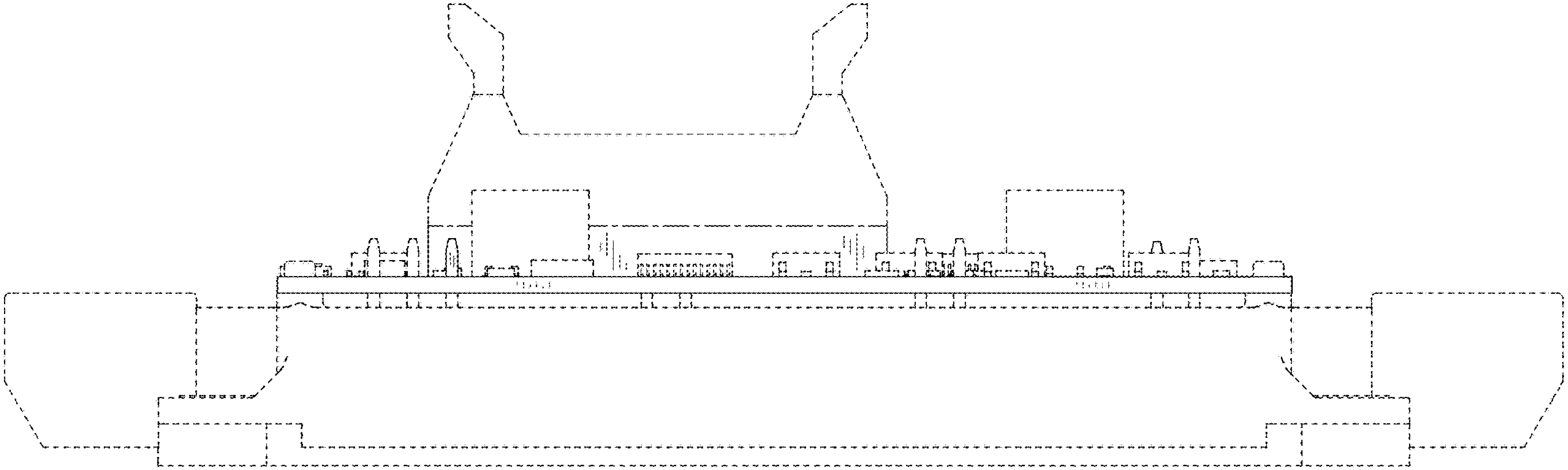


FIG.9



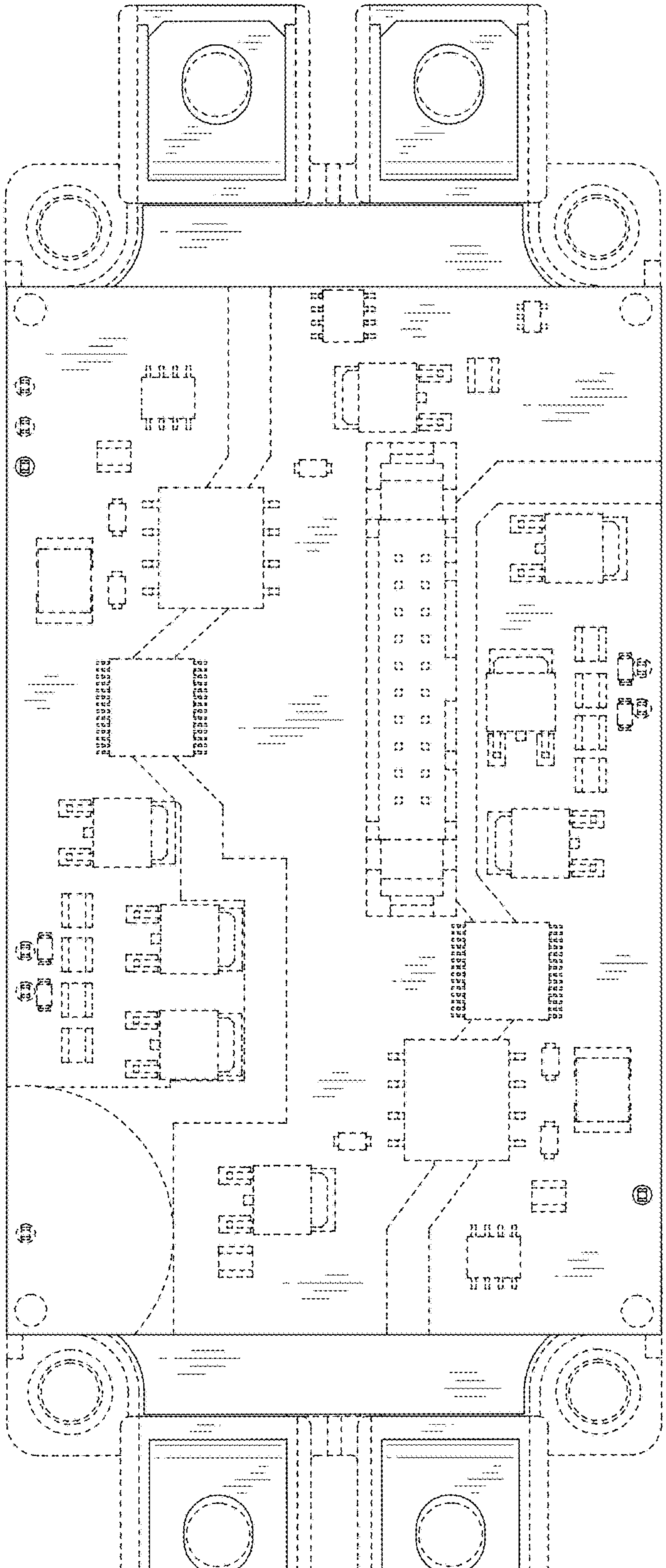


FIG.10

FIG.11

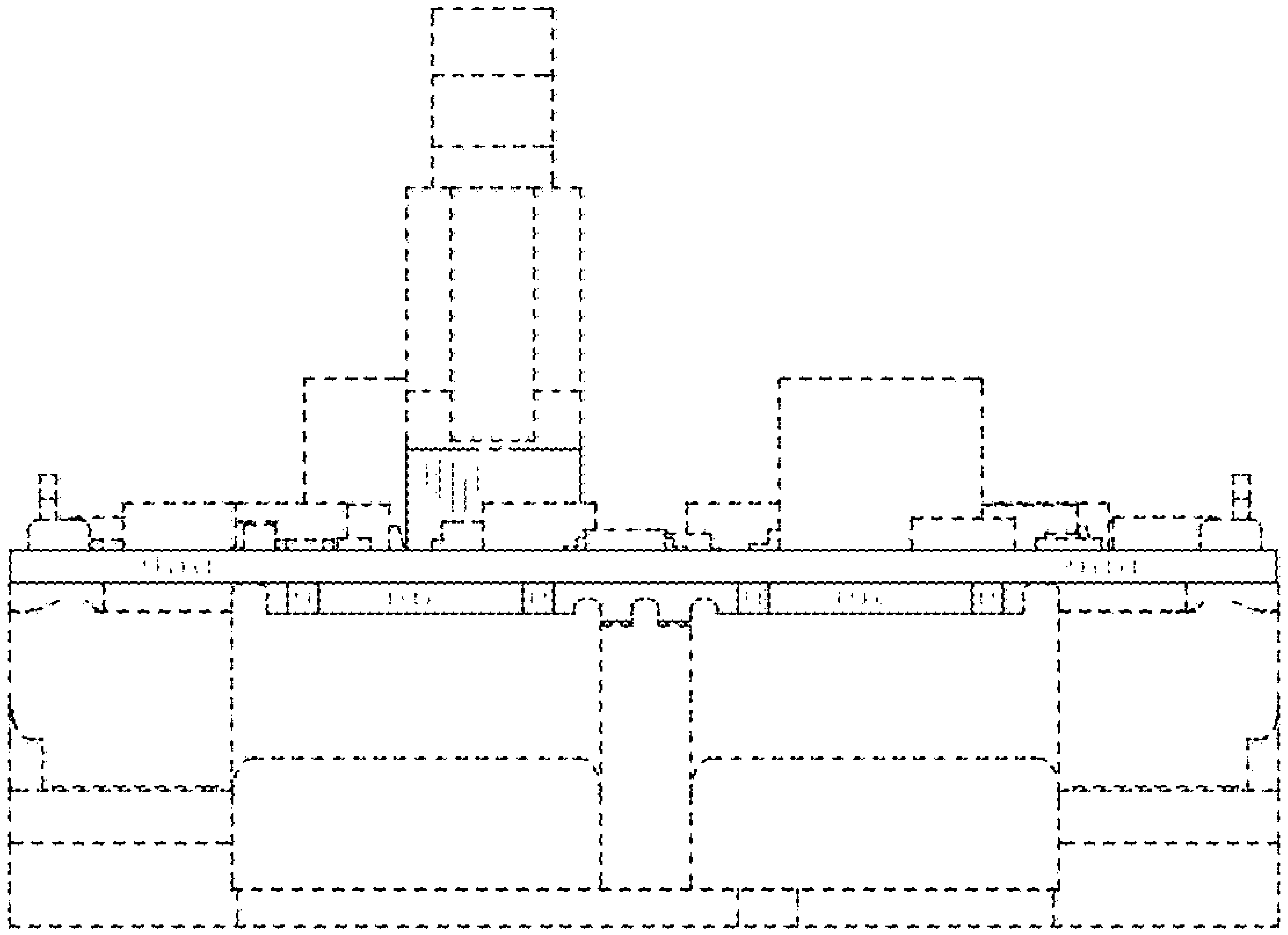


FIG.12